

# **LG-245PD2C-677K**

## **DATA SHEET**

SPEC. NO. : SZ19121803  
DATE : 2019/12/18  
REV. : A/0

Approved By:

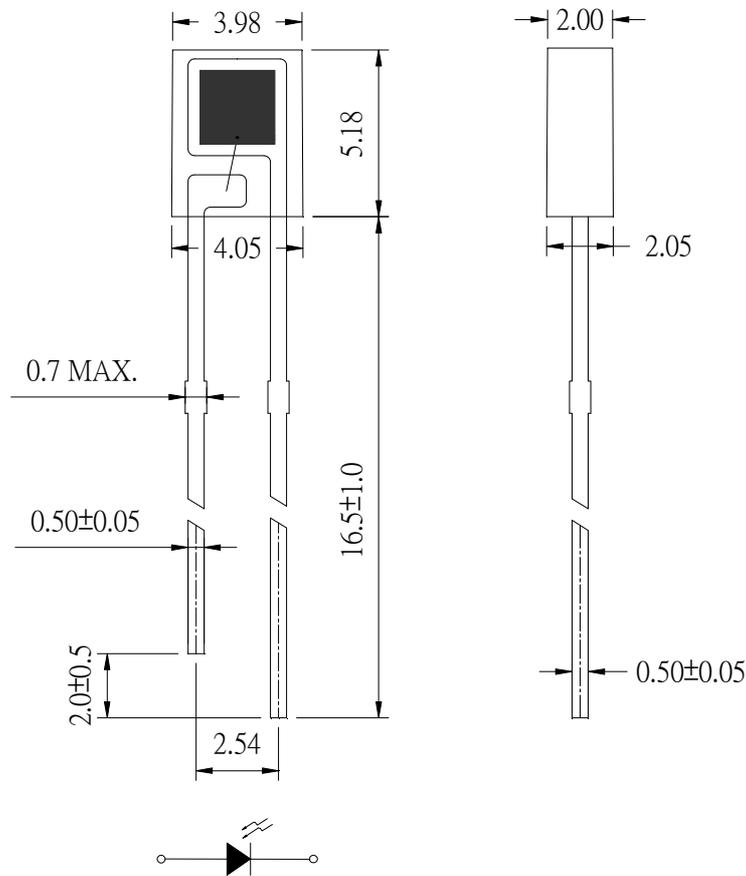
Checked By:

Prepared By:

## Feature

- ◆ Pb free product—RoHS compliant
- ◆ High Photo Sensitivity
- ◆ General purpose leads
- ◆ Reliable and rugged
- ◆ Long life – solid state reliability

## Package Dimensions



Part NO.	Chip Material	Lens Color
LG-245PD2C-677K	Silicon	Water Clear

### Notes:

1. All dimensions are in millimeters.
2. Tolerance is ±0.20mm unless otherwise noted.
3. Protruded resin under flange is 1.0mm max.
4. Lead spacing is measured where the leads emerge from the package.
5. Specifications are subject to change without notice.

## Absolute Maximum Ratings at Ta=25°C

Parameter	Maximum Rating	Unit
Power Dissipation	150	mW
Reverse Voltage	30	V
Electrostatic Discharge (HBM) <sup>*3</sup>	8000	V
Operating Temperature	-40°C~+85°C	
Storage Temperature Range	-40°C~+100°C	
Lead Soldering Temperature [2mm From Body]	260°C for 3 Seconds	
Lead Soldering Temperature [5mm From Body]	260°C for 5 Seconds	

### 1. Storage:

The storage ambient for the LEDs should not exceed 30°C temperature or 70% relative humidity.

It is recommended that LEDs out of their original packaging are used within three months.

For extended storage out of their original packaging, it is recommended that the LEDs be stored in a sealed container with appropriate desiccant or in desiccators with nitrogen ambient.

### 2. Precautions in handling:

- When soldering, leave 2mm of minimum clearance from the resin to the soldering point.
- Dipping the resin to solder must be avoided.
- Correcting the soldered position after soldering must be avoided.
- In soldering, do not apply any stress to the lead frame particularly when heated.
- When forming a lead, make sure not to apply any stress inside the resin.
- Lead forming must be done before soldering.
- It is necessary to cut the lead frame at normal temperature.

### 3. Caution in ESD:

Static Electricity and surge damages the LED. It is recommend to use a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.

## Electrical Optical Characteristics at Ta=25°C

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNITS	TEST CONDITIONS
Spectral Sensitivity	$\lambda$	400	---	1050	nm	/
Reverse Light Current	$I_L$	15.5	25	---	$\mu$ A	$V_R=5V$ $E_e=1mW/cm^2$ $\lambda_p=940nm$
Reverse Dark Current	$I_D$	---	---	30	nA	$V_R=10V$ $E_e=0mW/cm^2$
Reverse Voltage	$V_{(R)}$	30	---	---	V	$I_R=100\mu A$
Forward Voltage	$V_F$	---	---	1.5	V	$I_F=20mA$
Viewing Angle(X)	$2\theta_{1/2}$	---	120	---	Deg.	(Note 1)
Viewing Angle(Y)	$2\theta_{1/2}$	---	120	---	Deg.	
Rise Time/ Fall Time	tr/tf	---	50	---	ns	$V_R=10V$ $RL=1k\Omega$

### Note:

- $\theta_{1/2}$  is the off-axis angle at which the Reverse Light Current is half the axial Reverse Light Current.
- The  $I_L$  guarantee should be added  $\pm 15\%$  tolerance.

### Recommended soldering conditions:

	Wave Soldering (Pb Free)	Soldering Iron
Pre-heat Temperature	100°C Max.	---
Pre-heat Time	60sec. Max.	---
Peak Temperature	260°C Max.	300°C Max.
Dwell Time	5sec. Max. (one time only)	3sec. Max. (one time only)

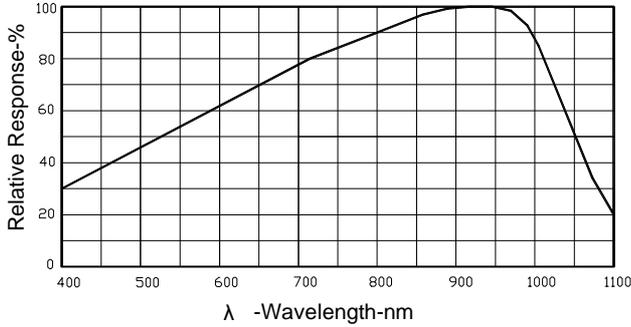
### Notes:

Excessive soldering temperature and/or time might result in deformation of the LED lens or catastrophic failure of the LED. IR reflow is not suitable process for the LED lamp product.

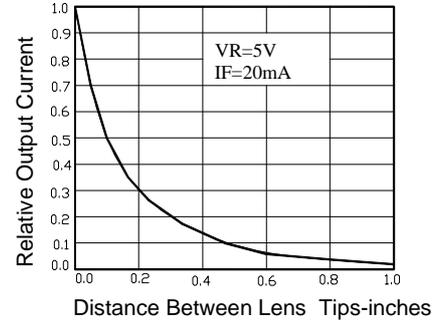
## Typical Electrical / Optical Characteristics Curves

(25°C Ambient Temperature Unless Otherwise Noted)

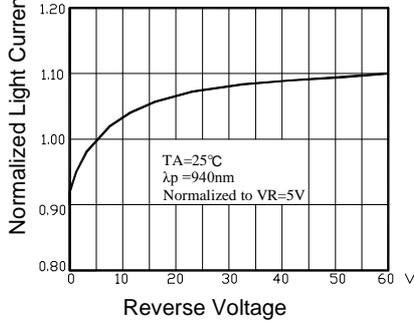
Relative Response vs. Wavelength



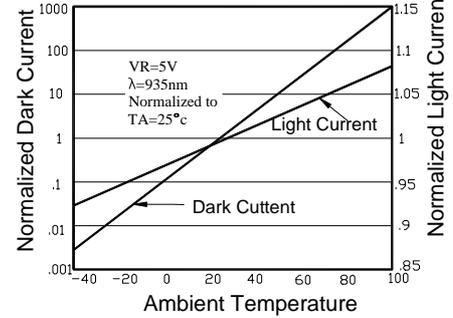
Coupling Characteristics



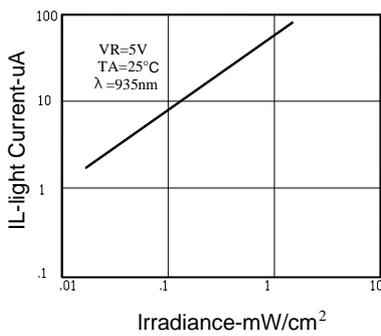
Normalized Light Current vs Reverse Voltage



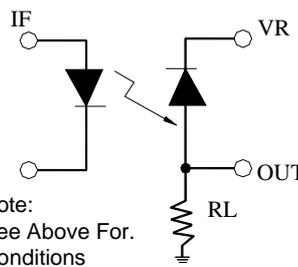
Normalized Light and Dark Current vs Ambient Temperature



Light Current vs. Irradiance

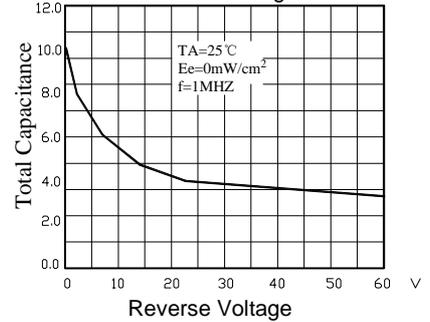


Switching Time Test Circuit

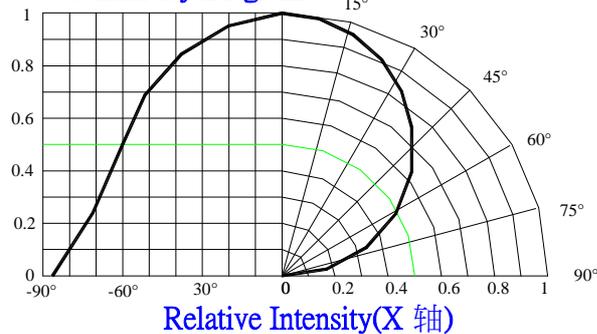


Note:  
See Above For.  
Conditions

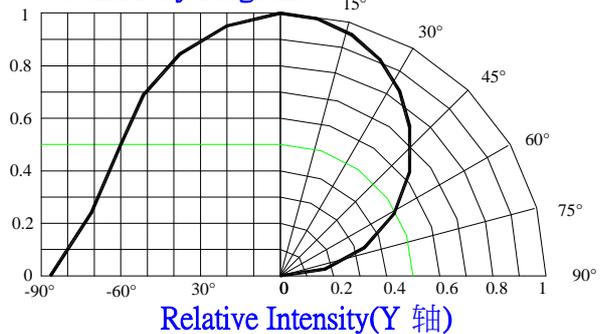
Total Capacitance vs Reverse Voltage



Sensitivity Diagram



Sensitivity Diagram



## LED MOUNTING METHOD

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures (Fig.1).

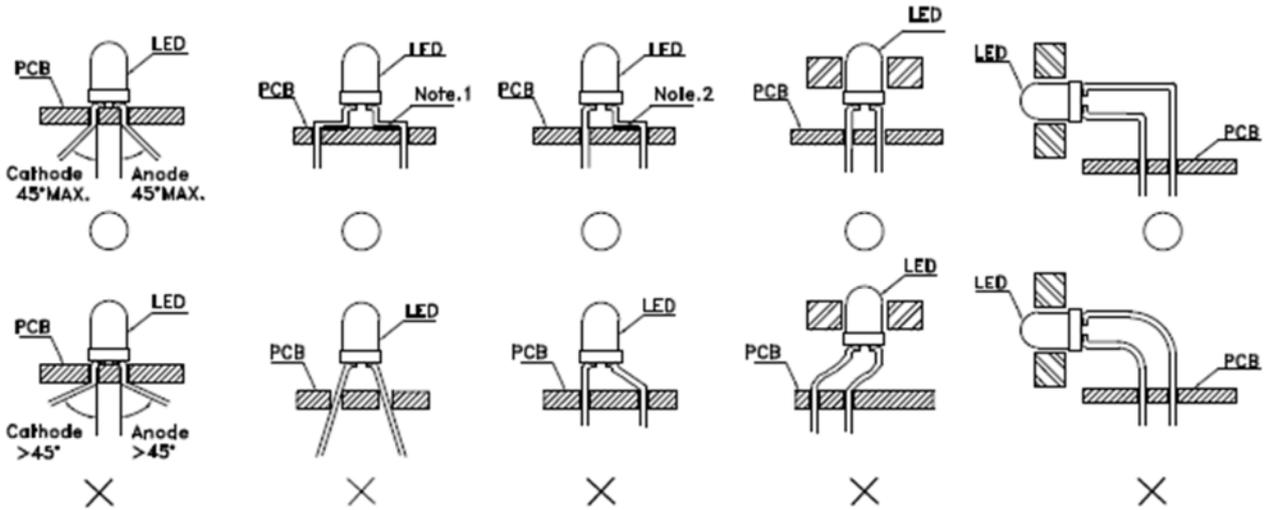


Fig. 1

“o” Correct mounting method “x” Incorrect mounting method

Note 1-2: Do not route PCB trace in the contact area between the lead frame and the PCB to prevent short-circuits.

2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit (Fig.2).

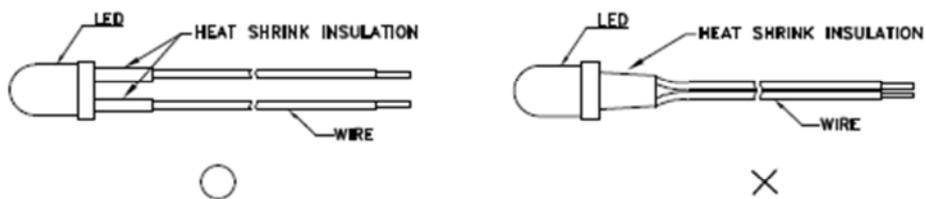


Fig. 2

3. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.

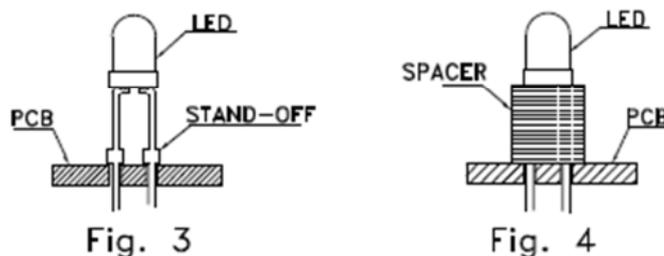


Fig. 3

Fig. 4

## LEAD FORMING PROCEDURES

1. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend (Fig.5 and Fig.6).

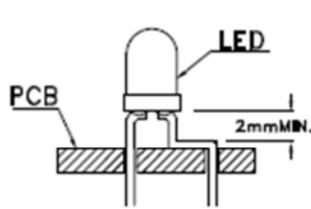


Fig. 5

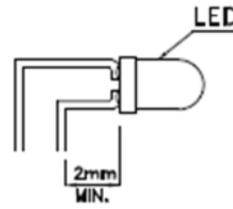


Fig. 6

2. Lead forming or bending must be performed before soldering, never during or after soldering.

3. Do not stress the LED lens during lead-forming in order to fractures in the lens epoxy and damage the internal structures.

4. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB (Fig.7).

5. Do not bend the leads more than twice (Fig.8).

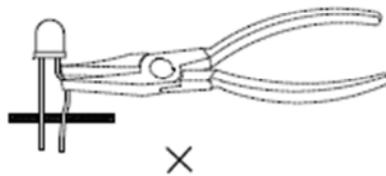


Fig. 7

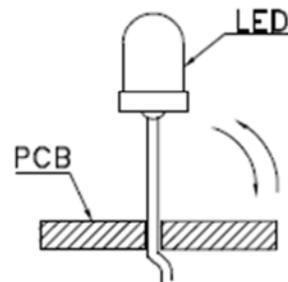


Fig. 8

6. After soldering or other high-temperature assembly, allow the LED to cool down to 50°C before applying outside force (Fig.9). In general, avoid placing excess force on the LED to avoid damage. For any questions please consult with LIGHT representative for proper handling procedures.

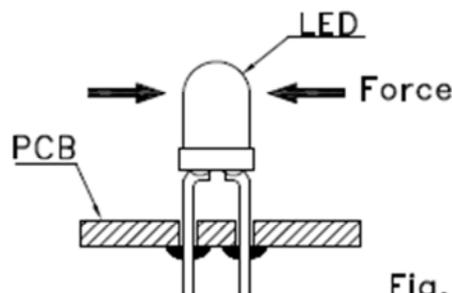
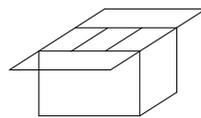
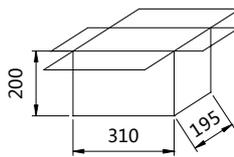
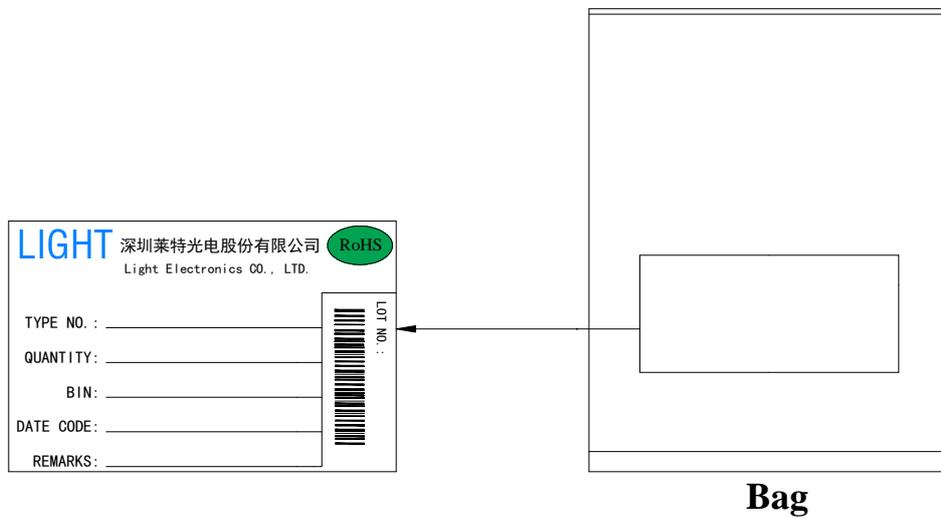
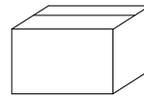


Fig. 9

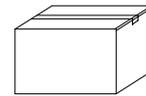
## PACKAGE



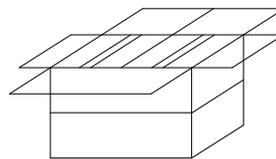
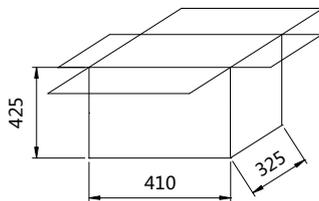
1



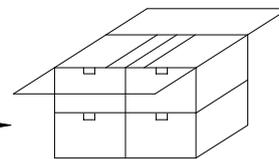
2



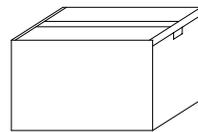
3



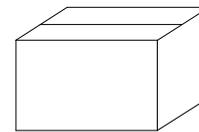
1



2



4



3

Bag minimum volume (pcs / Bag)	Bag volume (pcs / Bag)	Inner carton volume (Bags / carton)	Outer carton volume (Boxes / Carton)
500	1000	20	4

## Others

The appearance and specifications of the product may be modified for improvement, without prior notice.